

Product Texts

Platamid® M 995 Pellets

Copolyamide Hot Melt Adhesive /Extrusion Applications

Platamid® M 995 Pellets is a standard thermoplastic copolyamide hot melt adhesive available in pellet form. This high melt viscosity grade is particularly suitable for manufacturing of films and masterbatches.

Platamid® M 995 Pellets offer very good adhesion to various polar substrates (thermoplastics, thermosets, metal, natural fibers, etc).

AVAILABLE GRADES

This grade is available:

- dried (M 995 T)
- undried (M 995 F)

PACKAGING

Platamid® M 995 T and Platamid® M 995 F are delivered in 25 kg sealed bags.

These grades are ready to be processed

SHELFLIFE

Two years from the date of delivery. For any use above this limit, please refer to our technical services.

Processing/Physical Characteristics	dry / cond	Unit	Test Standard
ISO Data			
^[C] Melt volume-flow rate, MVR	2 / *	cm ³ /10min	ISO 1133
Temperature	160 / *	°C	-
Load	2.16 / *	kg	-

[C]: CAMPUS

Thermal properties	dry / cond	Unit	Test Standard
ISO Data			
^[C] Melting temperature, 10°C/min	144 / *	°C	ISO 11357-1/-3

[C]: CAMPUS

Characteristics

Processing

Film Extrusion

Features

Good Adhesion, Copolymer

Delivery form

Pellets

Regional Availability

North America, Europe, Asia Pacific, South and Central America, Near East/Africa